

Quarterly Reliability Monitoring Results

Quarters: Q1/2023 to Q4/2024

Based on structural similarity

| Supplier                  |  | User Part Number   |                                   |           |            |           |
|---------------------------|--|--|-----------------------------------|-----------|------------|-----------|
| Nexperia B.V.             |  | RB520CS30L   |                                   |           |            |           |
| Name of Laboratory        |  | Part Description   |                                   |           |            |           |
| Assembly reliability labs |  | Nexperia DHAM Schottky MCD package   |                                   |           |            |           |
| Based on AEC-Q101 Test    |  | Test Conditions  | Duration                          | # Lots    | # Quantity | # Rejects |
| # E1                      | <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test         | Tamb = 25 °C   | N/A                               | see below | all parts  | see below |
| # A1                      | <b>PC</b><br>Preconditioning                                   | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering                         | 24 hours<br>168 hours<br>3 cycles | 220       | 9400       | 0         |
| # B1                      | <b>HTRB</b><br>High Temperature Reverse<br>Bias                | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage <sup>[1]</sup> | 1000 hours                        | 231       | 9240       | 0         |
| # A4                      | <b>TC</b><br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C  | 1000 cycles                       | 57        | 2280       | 0         |
| # A3 or                   | <b>UHAST</b><br>Unbiased HAST                                  | JESD22-A118<br>Tamb = 130 °C, RH = 85 %  | 96 hours                          | 57        | 2280       | 0         |
| # A3 alt                  | <b>AC</b><br>Autoclave   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                                   |                                   |           |            |           |
| # A2 alt                  | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1], [2]</sup>             | 1000 hours                        | 57        | 2280       | 0         |
| # A5                      | <b>IOL</b><br>Intermittent Operating Life                      | MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure ΔTj =<br>100 °C for 15000 cycles            | 1000 hours                        | 49        | 2560       | 0         |
| # C8                      | <b>RSH</b><br>Resistance to Solder Heat                        | JESD22-A111<br>260 °C ± 5 °C   | 10 s                              | n.a.      | n.a.       | n.a.      |
| # C10                     | <b>SD</b><br>Solderability                                     | J-STD-002  |                                   | 28        | 840        | 0         |

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab        | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------|----------|---------|--------------------|------------|
| Nexperia<br>DHAM | Schottky   | 9240     | 0       | 0,46               | 2,18E+09   |

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